

Patent Abstracts of Japan

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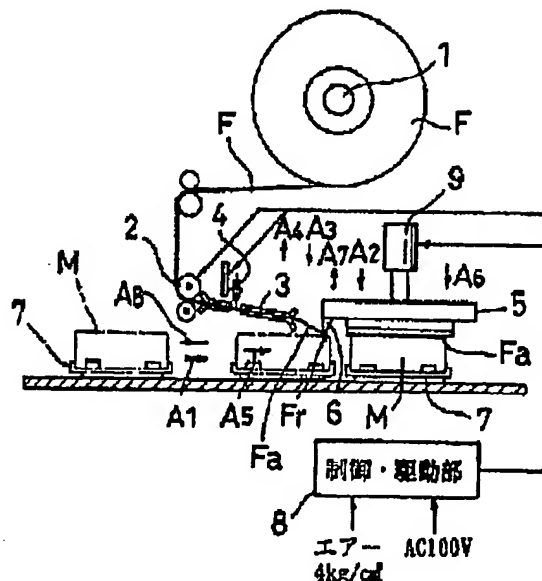
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TITLE : METHOD FOR SEALING MICRO  
PLATE, AND AUTOMATIC SEALING  
DEVICE FOR MICRO PLATE



**ABSTRACT :** PROBLEM TO BE SOLVED: To prevent generation of troubles at the time of the stacking and the robot operation by correctly positioning a heat bonding film piece on an upper surface of a micro plate to be continuously fed, and pressing and heat-bonding it at a stroke to completely seal each small hole chamber in a short time, and prevent the film from being projected from its peripheral edge.

**SOLUTION:** A long heat-bonding film F having the width not larger than the width of a micro plate M to be fed out of a film feed part 2 is cut into a heat-bonding film piece Fa of the length not larger than the length of the micro plate M in a cutter part 4, the forward feed of the micro plate M by a micro plate carriage part 7 is synchronized with the feed of the heat-bonding film F, and a forward edge Fr of the heat-bonding film piece Fa is heat-bonded to a forward edge of the micro plate M to be fed and temporarily fixed thereto. In a heat-press part 5, a whole surface of the heat-bonding film piece to cover a full opening of a large number of small hole chambers on an upper surface of the micro plate M is pressed and heat-bonded, and each small hole chamber is sealed in a single step.

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